

Appl. No. 10/659,415
Amdt. dated July 14, 2005
Reply to Office action of April 18, 2005

Remarks/Arguments

Applicants thank Examiner Stoner for his careful examination of this application and clear explanation of the claim rejections; for allowing claims 9-17 and for conditionally allowing claims 4, 5, 7, and 8. In response, applicants amend claim 1 to overcome the 102 rejection.

Claim 1

Claim 1 describes a method of stud bumping that includes the steps of engaging the plurality of wires substantially simultaneously with respective ones of a first set of the bond pads; and forming a first set of stud bumps substantially simultaneously outwardly from respective ones of the first set of the bond pads. The cited prior art reference Murata paper does not disclose at least these steps.

The Murata paper discloses a method to electrically insulative fine wires from outer environment by winding an insulating wire around a conductive wire.¹

As noted by Examiner Stoner, the capillary in the Murata paper does have multiple through holes. It is clear from the Constitution and the Drawing figures in the publication that the method discloses forming a wire bond between terminal 11 and terminal 7. The conductive wire 1 and the non-conductive wire 4 are fitted in the same capillary through the multiple through holes such that the non-conductive wire can wind itself around the conductive wire. However, the Murata paper does not disclose forming a set of stud bumps simultaneously by engaging the plurality of wires simultaneously with a set of bond pads.

Because the Murata paper fails to disclose at least these steps, it does not anticipate claim 1 and claim 1 stands patentable over the Murata reference.

Claims 2, 3, and 6

Claims 2, 3, and 6 properly depend from claim 1 and they stand patentable at least by virtue of their dependency.

¹ See JP405102228A, Abstract.

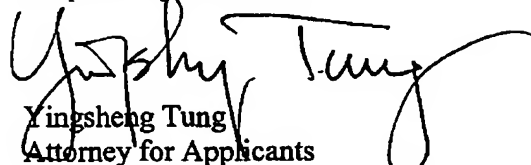
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Claims 18, 19, and 20

Claims 18-20 properly depend from claim 17. Since there is no rejection or objection to them, they stand patentable also.

In summary, applicants respectfully submit that this application is in allowable form; claim 1, as amended, and its dependent claims 2, 3, and 6 stand patentable because the Murata paper does not disclose all the claim limitations in claim 1. Applicants respectfully request further examination of this application and timely allowance of all pending claims.

Respectfully submitted,


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